

MMSZ4697

General Description

Half watt, General purpose, Medium Current Surface Mount Zener in the SOD-123 package. The SOD-123 package has the same footprint as the glass mini-melf (LL-34) package & provides a convenient alternative to the Leadless package.

Features

- Compact surface mount with same footprint as mini-melf
- 500mW rating on FR-4 or FR-5 board.
- Class 3 ESD rating (>16kV) per Human Body Model

Ordering

- 7 inch reel (178mm); 8mm Tape; 3,000 units per reel.

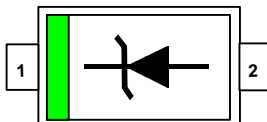
Absolute Maximum Ratings (Note 1) $T_A=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Value	Units
T_{STG}	Storage Temperature	-55 ~ 150	$^\circ\text{C}$
T_J	Maximum Junction Temperature	-55 ~ 150	$^\circ\text{C}$
P_D	Total Power Dissipation at 25°C Derate above 25°C	500 6.7	mW mW/ $^\circ\text{C}$
$R_{\theta JA}$	Thermal Resistance Junction to Ambient	340	$^\circ\text{C}/\text{W}$
$R_{\theta JL}$	Thermal Resistance Junction to Lead	150	$^\circ\text{C}/\text{W}$
ΔV_Z	Maximum Voltage Change (Note 2)	100	mV
Lead Solder Temperature (Max 10 second duration)		260	$^\circ\text{C}$
Nominal Zener Voltage (V_Z) at $50\mu\text{A}$		10	V

Note 1: These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

Note 2: Voltage change is equal to the difference between V_Z at $100\mu\text{A}$ and V_Z at $10\mu\text{A}$.

Top Mark: DE
1: Cathode
2: Anode

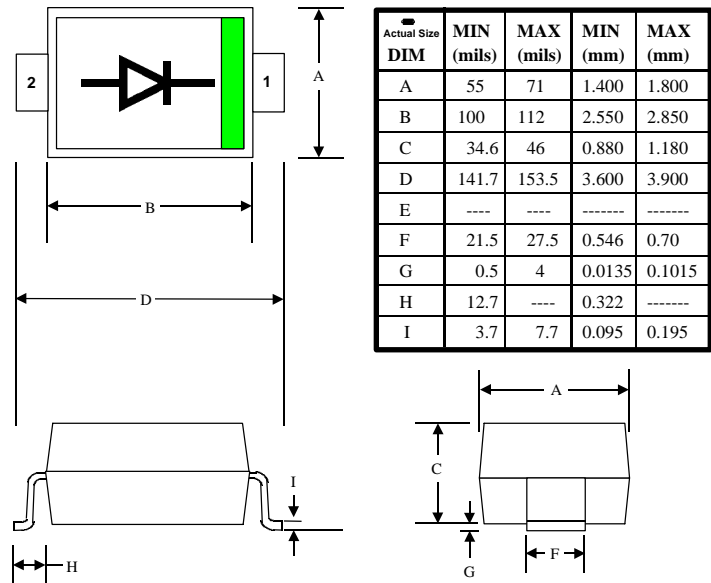


Electrical Characteristics $T_A=25^\circ\text{C}$ unless otherwise noted

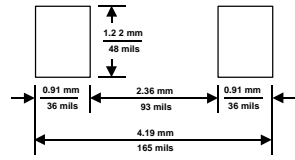
Symbol	Characteristics	Test Conditions	Min.	Max.	Units
V_Z	Zener Voltage	$I_{ZT} = 50\mu\text{A}$ D.C	9.50	10.50	V
I_R	Reverse Leakage	$V_R = 7.6\text{V}$		1.0	μA
V_F	Forward Voltage	$I_F = 10\text{mA}$		900	mV
ΔV_Z	Delta Zener Voltage (Note 2)	$I_{ZT} = 100\mu\text{A}$ to $10\mu\text{A}$		100	mV

SOD-123 PACKAGE
 PACKAGE CODE = (D6)
 Fairchild Semiconductor's Criteria

Corrected March 11, 1998



Actual Size DIM	MIN (mils)	MAX (mils)	MIN (mm)	MAX (mm)
A	55	71	1.400	1.800
B	100	112	2.550	2.850
C	34.6	46	0.880	1.180
D	141.7	153.5	3.600	3.900
E	----	----	-----	-----
F	21.5	27.5	0.546	0.70
G	0.5	4	0.0135	0.1015
H	12.7	----	0.322	-----
I	3.7	7.7	0.095	0.195



SOD-123 LAND PADS

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CoolFET™	FPST™	MicroFET™	PowerTrench®	SuperSOT™-6
CROSSVOLT™	FRFET™	MicroPak™	QFET®	SuperSOT™-8
DOMET™	GlobalOptoisolator™	MICROWIRE™	QS™	SyncFET™
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E ² CMOS™	HiSeC™	MSXPro™	Quiet Series™	TINYOPTO™
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FACT™	ImpliedDisconnect™	OCXPro™	RapidConnect™	UHC™
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Programmable Active Droop™			SPM™	

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